

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	119	((resin film) with (water wash\$4)) same (laser with (debris powder dust contaminat\$5))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/15 09:37
L2	67	1 and (semiconductor wafer silicon) with (laser cut\$4 saw\$4 etch\$4 street)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/15 09:33
L3	67	1 and (semiconductor wafer silicon) with (laser cut\$4 saw\$4 etch\$4 street divid\$4 division demarcate\$5 latic\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/15 09:34
L4	67	1 and (semiconductor wafer silicon chip) with (laser cut\$4 saw\$4 etch\$4 street divid\$4 division demarcate\$5 latic\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/15 09:34
L5	67	1 and (semiconductor wafer silicon chip) with (laser dic\$4 cut\$4 saw\$4 etch\$4 street divid\$4 division demarcate\$5 latic\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/15 09:54
L6	303	((resin film polyimide parylene polymer organic inorganic siob bsg siof insulat\$5 dielectric\$4 (low adj k)) with (solub\$6 water wash\$4)) same (laser with (debris powder dust contaminat\$5))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/15 09:40
L7	109	6 and (semiconductor wafer silicon chip) with (laser dic\$4 cut\$4 saw\$4 etch\$4 street divid\$4 division demarcate\$5 latic\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/15 10:01
L8	27	7 and film near2 coat\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/15 09:47
L9	5	7 and liquid with resin with rotat\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/15 09:49

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L10	0	6 and liquid with resin with rotat\$4 not 9	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/15 09:50
L11	4	(wafer with film with coat\$4) same (liquid with resin with rotat\$4 with (flow\$4 spread\$4))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/15 09:58
L12	1	("4806504").PN.	USPAT; USOCR	OR	OFF	2007/06/15 09:53
L13	1	12 and (spin\$5 rotat\$4 level\$4) with (liquid polymer\$4 resin\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/15 09:55
L14	20	"262024"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/15 09:59
L15	65	7 and (resin film polyimide parylene polymer organic inorganic siob bsg siof insulat\$5 dielectric\$4 (low adj k)) with (semiconductor wafer silicon chip) with (laser dic\$4 cut\$4 saw\$4 etch\$4 street divid\$4 division demarcat\$5 lattic\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/15 10:02